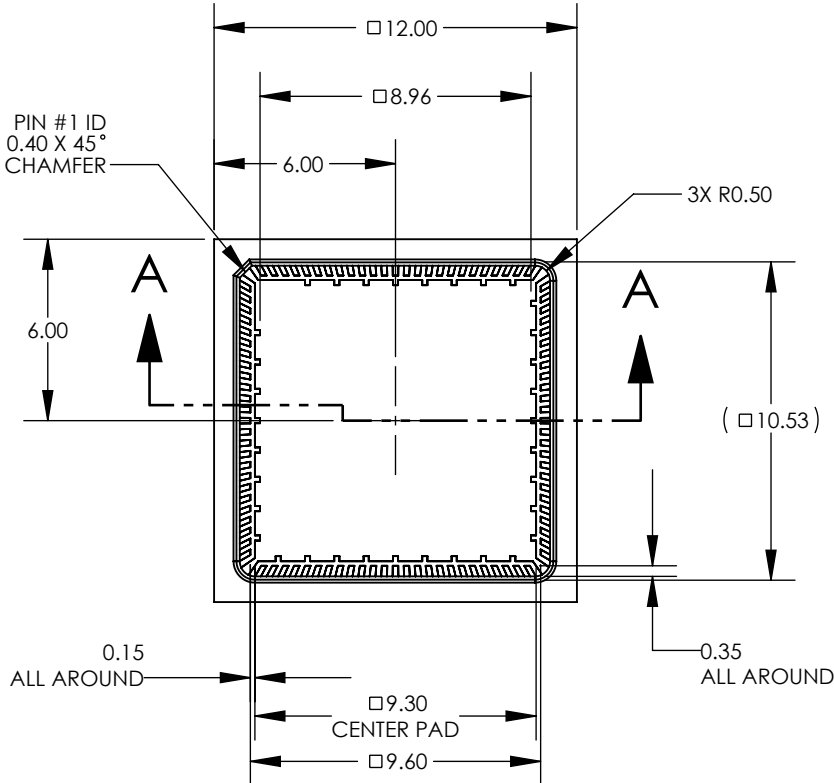
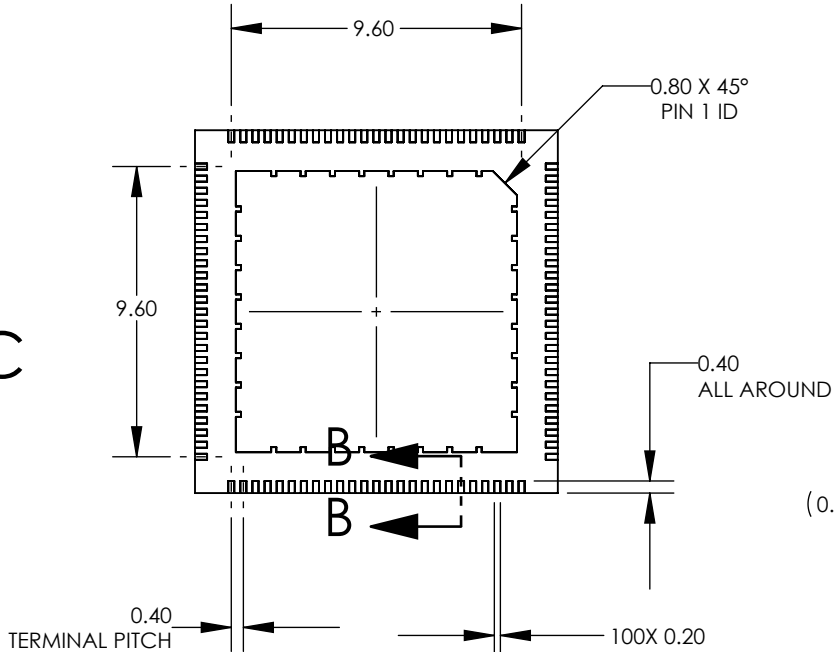


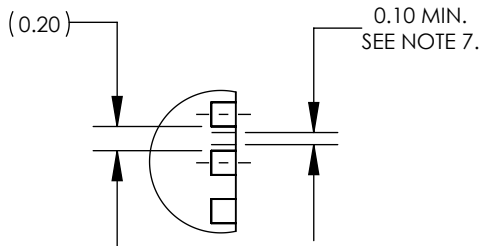
REVISIONS					
ZONE	REV.	DESCRIPTION	DATE	APPROVED	ECN NO.
	A	ORIGINAL RELEASE	1/13/2020	SS	
	B	ADJUSTED STANDARD TOLERANCE TO +/-0.05	9/29/2020	SS	QP751



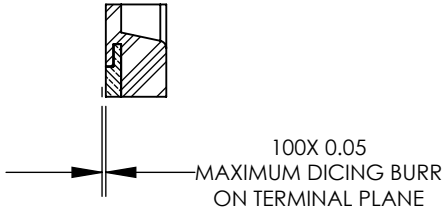
TOP VIEW



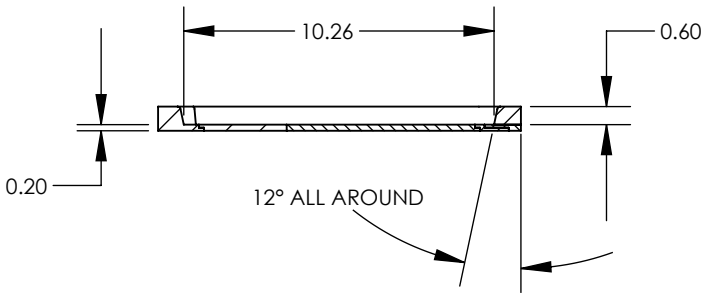
BOTTOM VIEW



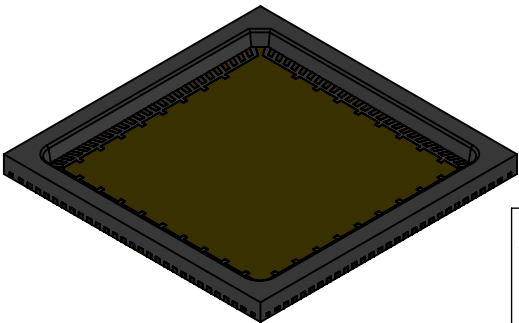
DETAIL C  
SCALE 16 : 1



SECTION B-B  
SCALE 10 : 1




SECTION A-A  
SCALE 4 : 1



NOTES:

- MATERIALS:  
LEAD FRAME: COPPER 194FH, WITH ADHESION ENHANCEMENT (A/E) THK = 0.203±0.008  
BODY: SHIN-ETSU KMC 2520L-M1 EPOXY MOLDING COMPOUND.
- LEAD FRAME FINISH: Ni/Pd/Au PER IPC-4556  
ELECTROLESS NICKEL: 5μ NOMINAL (3 - 6μ)  
ELECTROLESS PALLADIUM: 0.13μ NOMINAL (0.05 - 0.30μ)  
IMMERSION GOLD: 0.05μ NOMINAL (0.05 - 0.15μ)
- BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220
- COPPER SMEAR FROM DICING OPERATION CANNOT EXCEED 50% OF THE MOLD COMPOUND.

**PROPRIETARY AND CONFIDENTIAL**  
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		UNLESS OTHERWISE SPECIFIED:  DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:  ANGULAR: ±1 degree .XX: ±0.05		NAME	DATE	 <b>QPTECHNOLOGIES</b> <small>A DIVISION OF PROMEX INDUSTRIES   QPTECHNOLOGIES.COM</small>		
			DRAWN	S.SWEN	1/13/20	TITLE:  QP-QFN100-12MM-0.40MM WITH MINI-LOCKS		
			CHECKED	S.SWEN	1/13/20			
			ENG APPR.	S.SWEN	1/13/20			
			COMMENTS:			SIZE <b>B</b> DWG. NO. <b>501274</b> REV <b>B</b>		
		MATERIAL  SEE NOTE 1						
NEXT ASSY	USED ON	FINISH  SEE NOTE 2						
APPLICATION		DO NOT SCALE DRAWING	SCALE: 4:1   WEIGHT:   SHEET 1 OF 1					